



INNOLAS
solutions



MEMBER OF
**PHOTONICS
SYSTEMS
GROUP**

INNOVATION FOR THE
NEXT GENERATION



DIVIDOS Series

**LASER DEPANELING SYSTEMS
FOR THE ELECTRONIC INDUSTRY**

BENEFITS

- ◆ No tooling costs and better TCO
- ◆ Full cut with 30% more panels on board
- ◆ High edge quality and less residuals on board
- ◆ No carbonization and very residuals on board
- ◆ Cutting of any shape compared to mechanical cut
- ◆ Cost effective design
- ◆ Simple and easy to maintain
- ◆ Dedicated solution for PCB depaneling
- ◆ Industry 4.0 ready

OPTIONS

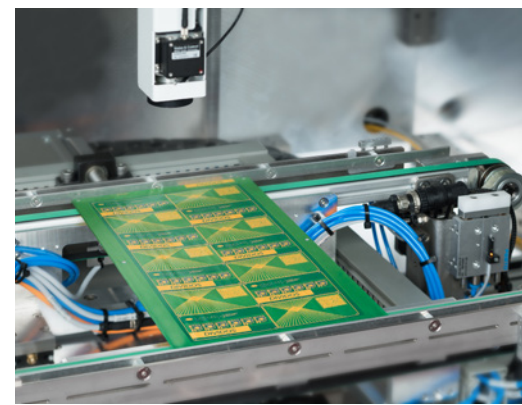
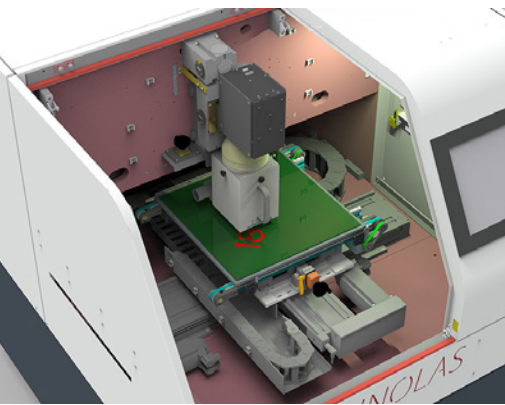
- ◆ 2nd process head (galvo scanner)
- ◆ Postprocessor for CAD file transfer
- ◆ Exhaust system
- ◆ MES Interface
- ◆ Different carrier options

TECHNOLOGY

- ◆ High speed Galvo Scanner
- ◆ Automatic calibration routines
- ◆ InnoLas μ Vision
- ◆ Windows 10 IoT
- ◆ Touch display

AUTOMATION

- ◆ Fully automated system
- ◆ Stand alone system
- ◆ S/ME/MA compliant



APPLICATIONS

Laser Depaneling/ Laser Routing

ACCURACY

< +/-50 μ m

SUBSTRATE

Dimension up to 18" x 18" (457 x 457 mm)

LASER

ns UV, ns green, ps IR

DIMENSIONS

Width: 1440 mm, Depth: 1521 mm;
Height: 1596 mm, Weight: 1100 kg

